



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC042NE7NS3 G		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA001420686						
<b>Package</b>		PG-TDSON-8-1		<b>Weight*</b>		122.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.414	3.61	3.61	36123	36123
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		309	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	copper	7440-50-8	37.762	30.89	30.93	309030	309432
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	469	469
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		653	
	plastics	epoxy resin	-	5.662	4.63		46334	
	inorganic material	silicondioxide	60676-86-0	34.130	27.93	32.63	279310	326297
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11880	11880
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1355	1355
solder	noble metal	silver	7440-22-4	0.087	0.07		712	
	non noble metal	tin	7440-31-5	0.070	0.06		569	
	non noble metal	lead	7439-92-1	3.322	2.72	2.85	27183	28464
CLIP plating	noble metal	silver	7440-22-4	1.289	1.06	1.06	10553	10553
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		93	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.26	9.27	92640	92761
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		183	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	copper	7440-50-8	22.292	18.24	18.27	182428	182666
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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